# Product End-of-Life Disassembly Instructions

## Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm motherboard</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
</tbody>
</table>
Components and waste containing asbestos
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screwdriver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble Main Battery
2. Dis-fasten KB Deck screw*4
3. Remove KB Deck
4. Dis-fasten keyboard screw*4
5. Pull out keyboard membrane
6. Remove keyboard
7. Dis-fasten Plamrest screw*3
8. Pull out touchpad ffc cable
9. Dis-fasten hdd screw*1
10. Remove hdd module
11. Pull out Lcd cable
12. Pull out antenna cable
13. Dis-fasten hinge screw*5
14. Remove Lcd module
15. Dis-fasten top frame screw*13
16. Pull out Power board cable
17. Remove top frame
18. Dis-fasten Hdd module screw*3
19. Remove Hdd module
20. Dis-fasten WLAN screw*2
21. Remove WLAN module
22. Pull out coin battery cable
23. Remove coin battery
24. Pull out speaker cable
25. Pull out DC cable
26. Pull out fan cable
27. Dis-fasten fan screw*2
28. Remove fan module
29. Dis-fasten thermal module screw*4
30. Remove thermal module
31. Dis-fasten PCB screw*1
32. Pull out USB board cable
33. Remove PCB
34. Dis-fasten speaker screw*2

PSG instructions for this template are available at [EL-MF877-01](#)
35. Remove speaker
36. Dis-fasten Lcd bezel screw*4
37. Remove Lcd bezel
38. Dis fasten Lcd module screw*6
39. Remove Lcd module

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

LCD panel disassembly procedure